

Amendments to the Claims

Please amend claims 1-3 and 10 and cancel claims 5-9 and 11-12, so that the claims read as follows:

1. (currently amended) A process for structuring a surface layer of ~~an object a semiconductor wafer~~ comprising:

applying bio-components to the surface of the ~~object bio-components that carry away surface material wafer~~, the bio-components being contained in at least one of a nutrient medium and an osmotic protective medium; ~~and~~

developing the bio-components on the surface differently depending on topography and/or chemical composition of the surface layer;

using the developed bio-components as a structure element of the semiconductor wafer; and

removing the at least one of a nutrient medium and an osmotic protective medium having the bio-components contained therein after the surface ~~material is carried away from the object surface of the semiconductor is structured.~~

2. (currently amended) The process of claim 1 wherein the bio-components ~~separate out a separation product and are adherently attached on the surface of the object wafer in the at~~ least one of a nutrient medium and an osmotic protective medium, the process further comprising:

removing the at least one of a nutrient medium and an osmotic protective medium with the bio-components contained therein after separating out ~~the a separation product from the object wafer surface.~~

3. (currently amended) The process of claim 2 wherein at least one of the ~~object wafer~~ and the surface layer comprises a non-biological material.

4. (original) The process of claim 2 wherein the bio-components are attached to the surface of a solid material.

5-9. (cancelled)

10. (currently amended) The process of claim 1 wherein at least one of the ~~object~~
wafer and the surface layer of the object comprises a non-biological material.

11-12. (cancelled)